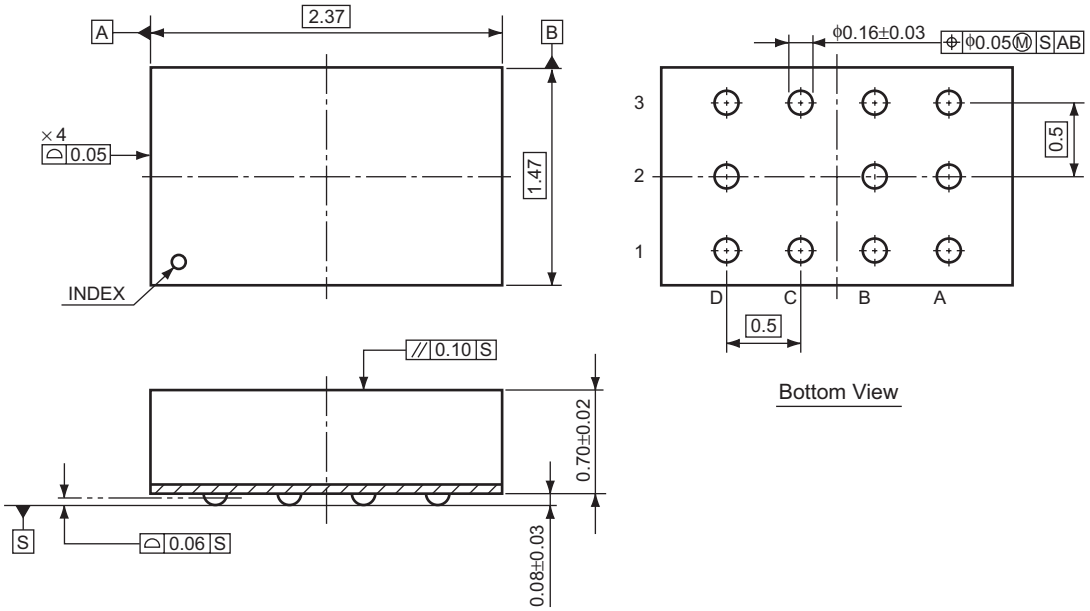
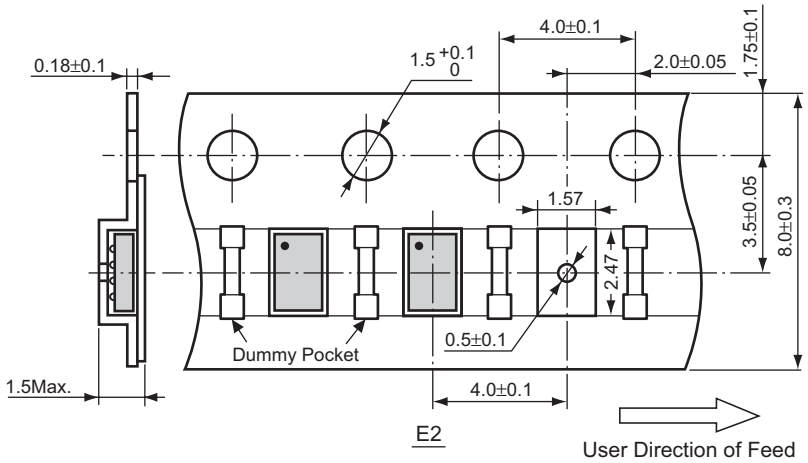
- **WLCSP-11-P2**

Unit: mm

PACKAGE DIMENSIONS

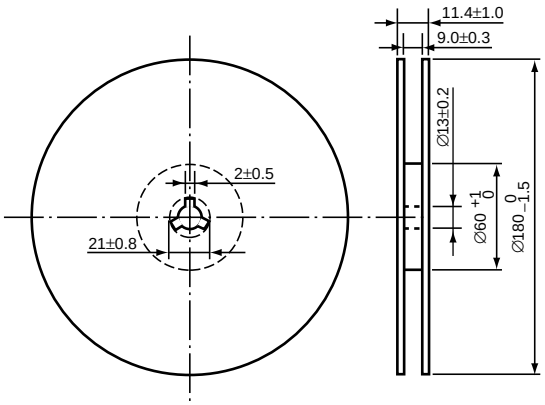


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-08Bc)

(1reel=4000pcs)



POWER DISSIPATION (WLCSP-11-P2)

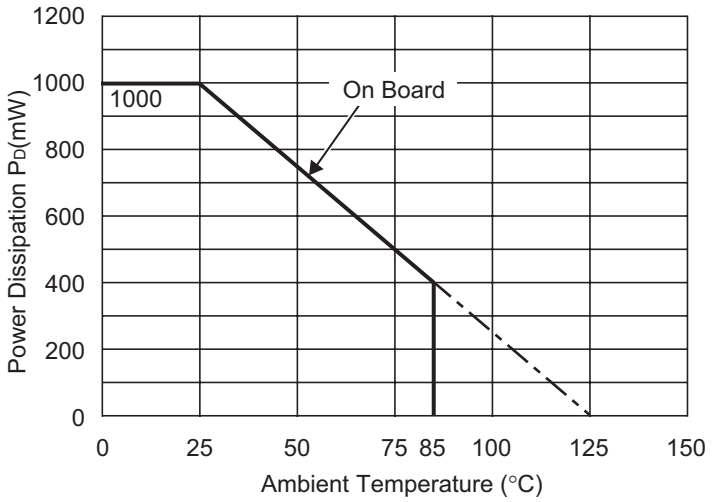
This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

Measurement Conditions

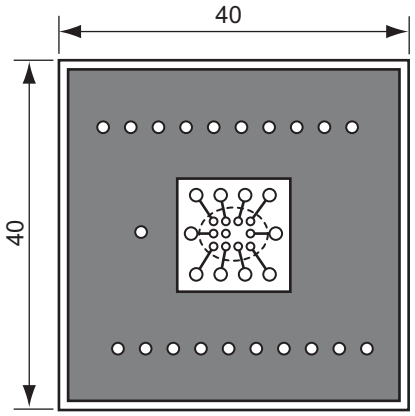
	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 80%, Back side : Approx. 90%
Through-hole	ϕ0.6mm × 31pcs

Measurement Result (Topt=25°C, Tjmax=125°C)

	Standard Land Pattern
Power Dissipation	1000mW
Thermal Resistance	θja=(125−25°C)/1W=100°C/W
Thermal Resistance	θjc=7°C/W



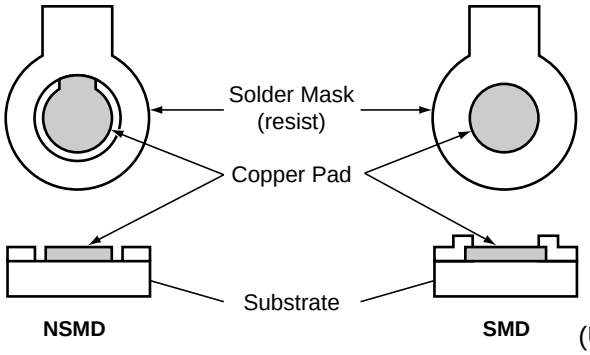
Power Dissipation



Measurement Board Pattern

IC Mount Area Unit : mm

RECOMMENDED LAND PATTERN



(Unit : mm)

NSMD and SMD Pad Definition

Pad definition	Copper Pad	Solder Mask Opening
NSMD (Non-Solder Mask defined)	0.20mm	Min. 0.30mm
SMD (Solder Mask defined)	Min. 0.30mm	0.20mm

* Pad layout and size can be modified by customers material, equipment, method.
* Please adjust pad layout according to your conditions.
* Recommended Stencil Aperture Size....ø0.3mm
* Since lead free WL-CSP components are not compatible with the tin/lead solder process, you shall not mount lead free WL-CSP components using the tin/lead solder paste.